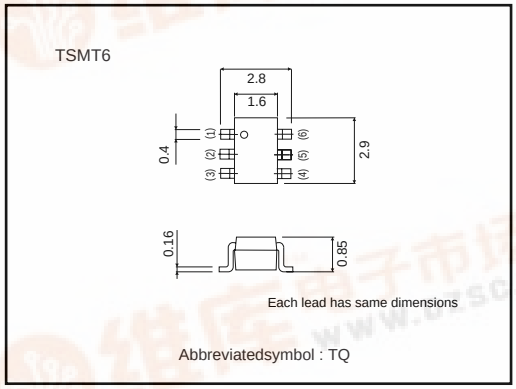
DC-DC Converter (−20V, −2.5A)

RTQ025P02

●Features

1) Low On-resistance.(140mΩ at 2.5V)
2) High Power Package.
3) High speed switching.
4) Low voltage drive.(2.5V)

●External dimensions (Units : mm)



●Applications

DC-DC converter

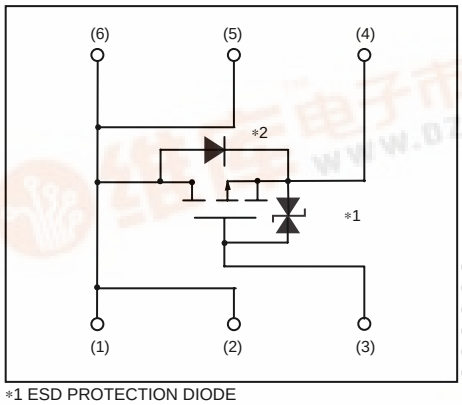
●Structure

Silicon P-channel
MOSFET

●Packaging specifications

Type	Package	Taping
	Code	TR
	Basic ordering unit (pieces)	3000
RTQ025P02		○

●Equivalent circuit



(1)DRAIN
(2)DRAIN
(3)GATE
(4)SOURCE
(5)DRAIN
(6)DRAIN

∗1 ESD PROTECTION DIODE
∗2 BODY DIODE

●**Absolute maximum ratings** (Ta=25°C)

Parameter		Symbol	Limits	Unit
Drain−source voltage		V_{DSS}	−20	V
Gate−source voltage		V_{GSS}	±12	V
Drain current	Continuous	I_D	±2.5	A
	Pulsed	I_{DP}	±10	A *1
Source current (Body diode)	Continuous	I_S	−1	A
	Pulsed	I_{SP}	−4	A *1
Total power dissipation		P_D	1.25	W*2
Channel temperature		Tch	150	°C
Range of Storage temperature		Tstg	−55~+150	°C

∗1 Pw≦10μs, Duty cycle≦1%
∗2 Mounted on a ceramic board

●**Electrical characteristics** (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Gate-source leakage	I_{GSS}	−	−	±10	μA	V_{GS}=±12V, V_{DS}=0V
Drain-source breakdown voltage	$V_{(BR)DSS}$	−20	−	−	V	I_D=−1mA, V_{GS}=0V
Zero gate voltage drain current	I_{DSS}	−	−	−1	μA	V_{DS}=−20V, V_{GS}=0V
Gate threshold voltage	$V_{GS(th)}$	−0.7	−	−2.0	V	V_{DS}=−10V, I_D=−1mA
Static drain-source on-state resistance	$R_{DS(on)}$ *	−	72	100	mΩ	I_D=−2.5A, V_{GS}=−4.5V
		−	80	110	mΩ	I_D=−2.5A, V_{GS}=−4V
		−	140	190	mΩ	I_D=−1.2A, V_{GS}=−2.5V
Foward transfer admittance	$\|Y_{fs}\|$ *	2.0	−	−	S	V_{DS}=−10V, I_D=−1.2A
Input capacitance	C_{iss}	−	580	−	pF	V_{DS}=−10V,V_{GS}=0V f=1MHz
Output capacitance	C_{oss}	−	110	−	pF	
Reverse transfer capacitance	C_{rss}	−	80	−	pF	
Turn-on delay time	$t_{d(on)}$ *	−	12	−	ns	I_D=−1.2A V_{DD}≒−15V V_{GS}=−4.5V R_L=12.5Ω R_{GS}=10Ω
Rise time	t_r *	−	20	−	ns	
Turn-off delay time	$t_{d(off)}$ *	−	40	−	ns	
Fall time	t_f *	−	17	−	ns	
Total gate charge	Qg	−	6.4	−	nC	V_{DD}≒−15V V_{GS}=−4.5V I_D=−2.5A
Gate-source charge	Qgs	−	1.4	−	nC	
Gate-drain charge	Qgd	−	1.9	−	nC	

∗PULSED

Body diode characteristics (source-drain characteristics)

Forward voltage	VSD	−	−	−1.2	V	I_S=−1A, V_{GS}=0V

●Electrical characteristic curves

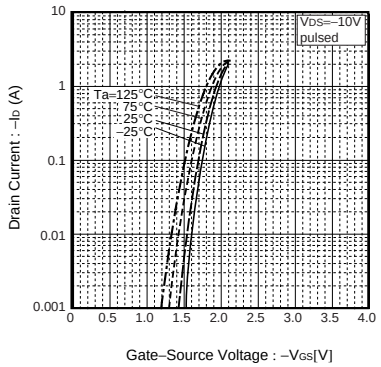


Fig.1 Typical Transfer Characteristics

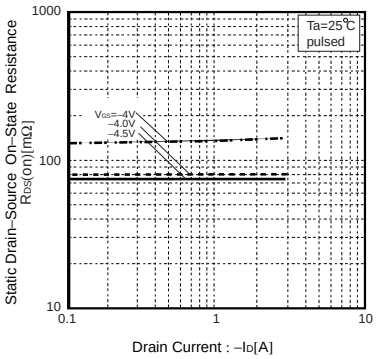


Fig.2 Static Drain–Source On–State Resistance vs.Drain Current

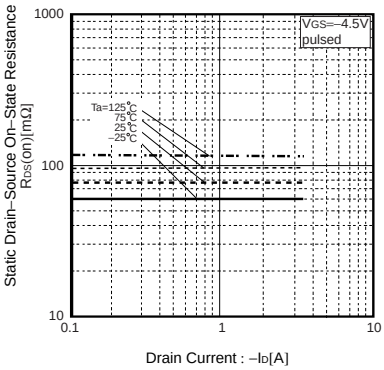


Fig.3 Static Drain–Source On–State Resistance vs.Drain Current

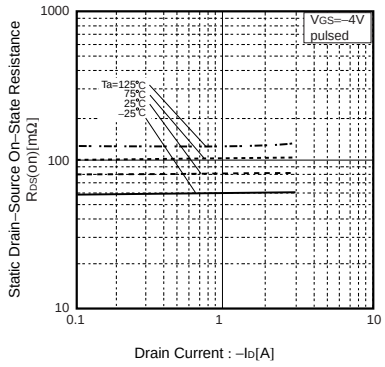


Fig.4 Static Drain–Source On–State Resistance vs.Drain–Current

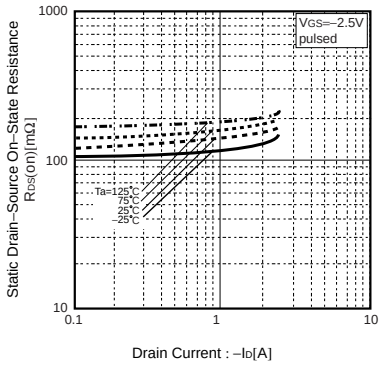


Fig.5 Static Drain–Source On–State Resistance vs.Drain–Current

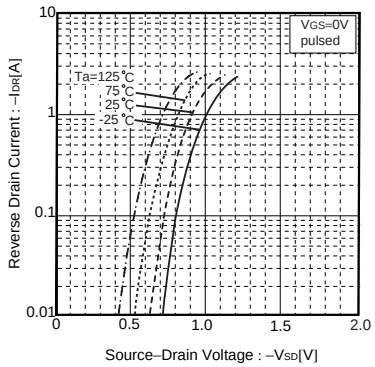


Fig.6 Reverse Drain Current vs. Source-Drain Voltage

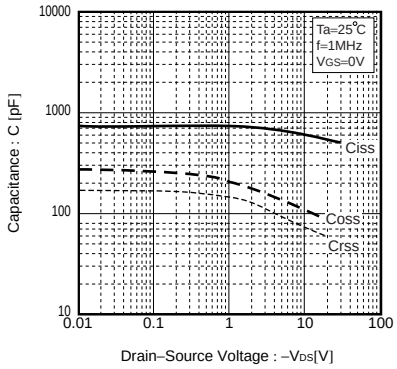


Fig.7 Typical Capactitance vs.Drain–Source Voltage

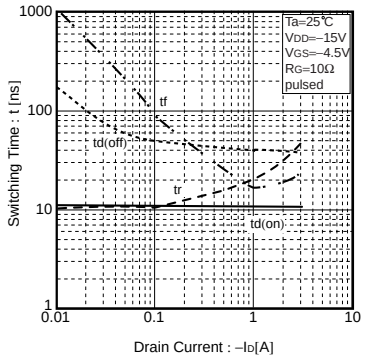


Fig.8 Switching Characteristics

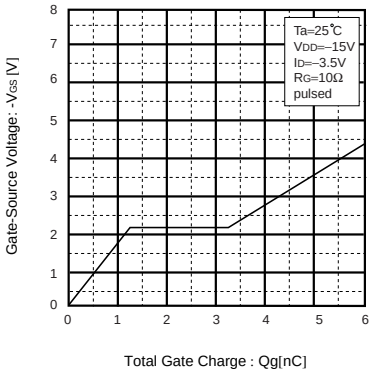


Fig.9 Dynamic Input Characteristics

●**Measurement circuits**

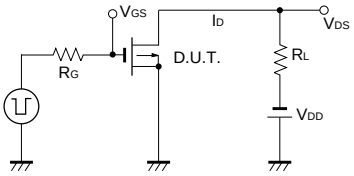


Fig.10 Switching Time Measurement Circuit

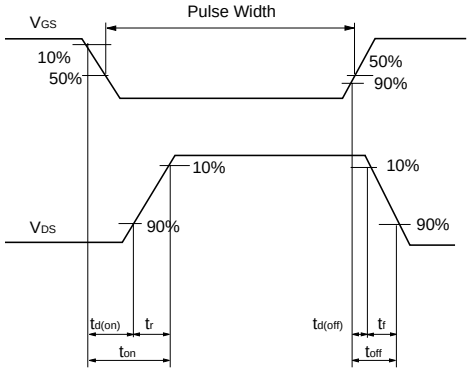


Fig.11 Switching Waveforms

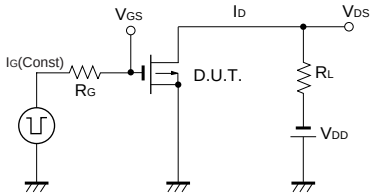


Fig.12 Gate Charge Measurement Circuit

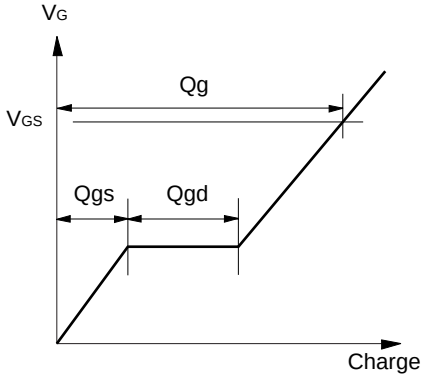


Fig.13 Gate Charge Waveforms

Notes

- No technical content pages of this document may be reproduced in any form or transmitted by any means without prior permission of ROHM CO.,LTD.
- The contents described herein are subject to change without notice. The specifications for the product described in this document are for reference only. Upon actual use, therefore, please request that specifications to be separately delivered.
- Application circuit diagrams and circuit constants contained herein are shown as examples of standard use and operation. Please pay careful attention to the peripheral conditions when designing circuits and deciding upon circuit constants in the set.
- Any data, including, but not limited to application circuit diagrams information, described herein are intended only as illustrations of such devices and not as the specifications for such devices. ROHM CO.,LTD. disclaims any warranty that any use of such devices shall be free from infringement of any third party's intellectual property rights or other proprietary rights, and further, assumes no liability of whatsoever nature in the event of any such infringement, or arising from or connected with or related to the use of such devices.
- Upon the sale of any such devices, other than for buyer's right to use such devices itself, resell or otherwise dispose of the same, no express or implied right or license to practice or commercially exploit any intellectual property rights or other proprietary rights owned or controlled by
- ROHM CO., LTD. is granted to any such buyer.
- Products listed in this document use silicon as a basic material.
  Products listed in this document are no antiradiation design.

The products listed in this document are designed to be used with ordinary electronic equipment or devices (such as audio visual equipment, office-automation equipment, communications devices, electrical appliances and electronic toys).
Should you intend to use these products with equipment or devices which require an extremely high level of reliability and the malfunction of with would directly endanger human life (such as medical instruments, transportation equipment, aerospace machinery, nuclear-reactor controllers, fuel controllers and other safety devices), please be sure to consult with our sales representative in advance.

About Export Control Order in Japan

Products described herein are the objects of controlled goods in Annex 1 (Item 16) of Export Trade Control Order in Japan.
In case of export from Japan, please confirm if it applies to "objective" criteria or an "informed" (by MITI clause) on the basis of "catch all controls for Non-Proliferation of Weapons of Mass Destruction.